

IN THE CLAIMS:

A. Please cancel claims 1-12 without prejudice or disclaimer.

B. Please add new claims 13-36 as follows:

13. (New) A method for surface mounting electrical components on a printed circuit board (PCB) with a surface mounter, comprising:  
locating a PCB at a first mounting position by moving the PCB in both the X and Y directions within a working area of the surface mounter;  
picking up a plurality of electrical components with a corresponding plurality of suction nozzles; and  
moving the plurality of suction nozzles simultaneously to mount the electrical components on the PCB.

14. (New) The method of claim 13, further comprising the steps of:

locating the PCB at a second mounting position within the working area of the surface mounter; and  
repeating the picking and moving steps.

15. (New) The method of claim 13, wherein the moving step comprises simultaneously moving the plurality of suction nozzles with respect to each other to mount the electrical components on the PCB.

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16. (New) The method of claim 13, wherein the moving step comprises simultaneously moving the plurality of suction nozzles with respect to each other in both the X and Y directions to mount the electrical components on the PCB.

17. (New) The method of claim 13, further comprising the steps of:  
    checking the alignment of the electrical components held by the plurality of suction nozzles; and  
    selectively rotating the suction nozzles and the held electrical components based on the results of the checking step before performing the moving step.

18. (New) The method of claim 13, wherein the locating step comprises:  
    transferring the PCB from a conveyer to a moving member; and  
    locating the moving member at the first mounting position.

19. (New) The method of claim 13, further comprising transferring the PCB from a first conveyer to a second conveyer before performing the locating step.

20. (New) The method of claim 19, further comprising transferring the PCB from the second conveyer back to the first conveyer after performing the moving step.

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21. (New) A method for surface mounting electrical components on a printed circuit board (PCB) with a surface mounter, comprising:

locating a PCB at a first mounting position within a working area of the surface mounter;

picking up a plurality of electrical components with a corresponding plurality of suction nozzles; and

moving the plurality of suction nozzles with respect to the PCB and with respect to each other to substantially simultaneously mount a plurality of the electrical components on the PCB.

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22. (New) The method of claim 21, further comprising the steps of:

locating the PCB at a second mounting position within the working area of the surface mounter; and

repeating the picking and moving steps.

23. (New) The method of claim 21, wherein the moving step comprises simultaneously moving the plurality of suction nozzles with respect to each other to mount the electrical components on the PCB.

24. (New) The method of claim 21, wherein the moving step comprises simultaneously moving the plurality of suction nozzles with respect to each other in both the X and Y directions to mount the electrical components on the PCB.

25. (New) The method of claim 21, further comprising the steps of:  
    checking the alignment of the electrical components held by the plurality of suction nozzles; and  
    selectively rotating the suction nozzles and the held electrical components based on the results of the checking step before performing the moving step.

26. (New) The method of claim 21, further comprising transferring the PCB from a first conveyer to a second conveyer before performing the locating step.

27. (New) The method of claim 26, further comprising transferring the PCB from the second conveyer back to the first conveyer after performing the moving step.

28. (New) A method for surface mounting electrical components on a printed circuit board (PCB) with a surface mounter, comprising:  
    locating a PCB at a first mounting position within a working area of the surface mounter;

picking up a plurality of electrical components with a corresponding plurality of mounter heads, wherein the plurality of mounter heads are coupled to a corresponding plurality Y-frames, wherein the plurality of Y-frames are movably mounted on a single X-frame such that the Y-frames are movable along the X-frame in the X direction with respect to each other, and wherein the plurality of mounter heads are also movable in the Y direction along their corresponding Y-frames; and

moving the plurality of mounter heads to mount the electrical components on the PCB.

29. (New) The method of claim 28, further comprising the steps of:

locating the PCB at a second mounting position within the working area of the surface mounter; and

repeating the picking and moving steps.

30. (New) The method of claim 28, wherein the moving step comprises moving the plurality of mounter heads with respect to each other to mount the electrical components on the PCB.

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31. (New) The method of claim 28, wherein the moving step comprises moving the plurality of mounter heads with respect to each other in both the X and Y directions to mount the electrical components on the PCB.

32. (New) The method of claim 28, wherein the moving step comprises simultaneously moving the plurality of mounter heads to mount the electrical components of the PCB.

33. (New) The method of claim 28, wherein the moving step comprises moving the plurality of mounter heads to substantially simultaneously mount a plurality of the electrical components on the PCB.

34. (New) The method of claim 28, further comprising the steps of:  
    checking the alignment of the electrical components held by the plurality of mounter heads; and  
    selectively rotating the electrical components held by the mounter heads, based on the results of the checking step, before performing the moving step.

35. (New) The method of claim 28, further comprising transferring the PCB from a first conveyer to a second conveyer before performing the locating step.

36. (New) The method of claim 35, further comprising transferring the PCB from the second conveyer back to the first conveyer after performing the moving step.

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